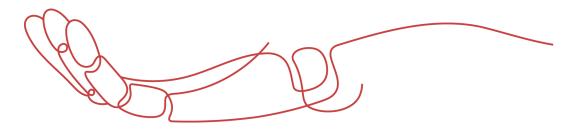


# **PRODUCT DATA SHEET**



To learn more about JGSEMI, please visit our website at



Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.



### **MMBT2222AW**

SURFACE MOUNT SILICON NPN TRANSISTOR



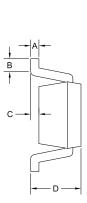
SOT-323

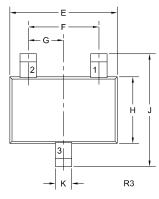
MAXIMUM RATINGS: (T <sub>A</sub> =25°C)		SYMBOL		UNITS				
Collector-Base Voltage		V <sub>CBO</sub>	75	V				
Collector-Emitter Voltage		V <sub>CEO</sub>	40	V				
Emitter-Base Voltage		V <sub>EBO</sub>	6.0	V				
Continuous Collector Current		I <sub>C</sub>	600	mA				
Power Dissipation		PD	275	mW				
Operating and Storage Junction Temperature		т <sub>Ј</sub> , Т <sub>stg</sub>	-65 to +150	°C				
Thermal Resistance		ΘJA	455	°C/W				
ELECTRICAL CHARACTERISTICS: (T <sub>A</sub> =25°C unless otherwise noted)								
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS				
IСВО	V <sub>CB</sub> =60V		10	nA				
ICBO	V <sub>CB</sub> =60V, T <sub>A</sub> =125°C		10	μA				
ICEV	$V_{CE}$ =60V, $V_{EB}$ =3.0V		10	nA				
I <sub>EBO</sub>	V <sub>EB</sub> =3.0V		10	nA				
BVCBO	Ι <sub>C</sub> =10μΑ	75		V				
BVCEO	I <sub>C</sub> =10mA	40		V				
BVEBO	Ι <sub>Ε</sub> =10μΑ	6.0		V				
VCE(SAT)	I <sub>C</sub> =150mA, I <sub>B</sub> =15mA		0.3	V				
VCE(SAT)	I <sub>C</sub> =500mA, I <sub>B</sub> =50mA		1.0	V				
V <sub>BE(SAT)</sub>	I <sub>C</sub> =150mA, I <sub>B</sub> =15mA	0.6	1.2	V				
V <sub>BE(SAT)</sub>	I <sub>C</sub> =500mA, I <sub>B</sub> =50mA		2.0	V				
hFE	V <sub>CE</sub> =10V, I <sub>C</sub> =0.1mA	35						
hFE	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA	50						
h <sub>FE</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA	75						
hFE	V <sub>CE</sub> =10V, I <sub>C</sub> =150mA	100	300					
hFE	V <sub>CE</sub> =1.0V, I <sub>C</sub> =150mA	50						
h <sub>FE</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =500mA	40						
fT	$V_{CE}$ =20V, I <sub>C</sub> =20mA, f=100MHz	300		MHz				



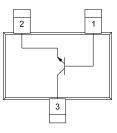
ELECTRIC	AL CHARACTERISTICS - Continued: (T <sub>A</sub> =25°C unle	ess otherwise note	ed)	
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
Cob	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1.0MHz		8.0	pF
C <sub>ib</sub>	V <sub>EB</sub> =0.5V, I <sub>C</sub> =0, f=1.0MHz		25	pF
h <sub>ie</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz	2.0	8.0	kΩ
h <sub>ie</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=1.0kHz	0.25	1.25	kΩ
	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz	0.20		
h <sub>re</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=1.0kHz		8.0	x10 <sup>-4</sup>
h <sub>re</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz		4.0	x10 <sup>-4</sup>
h <sub>fe</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=1.0kHz	50	300	
h <sub>fe</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =1.0mA, f=1.0kHz	75	375	
h <sub>oe</sub>	V <sub>CE</sub> =10V, I <sub>C</sub> =10mA, f=1.0kHz	5.0	35	μS
h <sub>oe</sub>	V <sub>CB</sub> =10V, I <sub>E</sub> =20mA, f=31.8MHz	25	200	μS
rb'C <sub>C</sub>	$V_{CE}$ =10V, I <sub>C</sub> =100µA, R <sub>S</sub> =1.0kΩ, f=1.0kHz		150	ps
NF	$V_{CC}$ =30V, $V_{BE}$ =0.5V, $I_{C}$ =150mA, $I_{B1}$ =15mA		4.0	dB
<sup>t</sup> d	V <sub>CC</sub> =30V, V <sub>BE</sub> =0.5V, I <sub>C</sub> =150mA, I <sub>B1</sub> =15mA V <sub>CC</sub> =30V, I <sub>C</sub> =150mA, I <sub>B1</sub> =I <sub>B2</sub> =15mA/ <sub>CC</sub> =30V,		10	ns
t <sub>r</sub>	$I_{C}=150$ mA, $I_{B1}=I_{B2}=15$ mA		25	ns
t <sub>s</sub>			225	ns
t <sub>f</sub>			60	ns

### SOT-323 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



	DIMENSIONS							
	DIMENSIONS							
		INCHES		MILLIMETERS				
5	SYMBOL	MIN	MAX	MIN	MAX			
	А	0.002	0.008	0.05	0.20			
	В	0.004	-	0.10	-			
	С	-	0.004	-	0.10			
	D	0.031	0.043	0.80	1.10			
	Е	0.071	0.087	1.80	2.20			
	F	0.051		1.30				
	G			0.65				
	Н	0.045	0.053	1.15	1.35			
	J	0.079	0.087	2.00	2.20			
	K	0.008	0.016	0.20	0.40			
Se	SOT-323 (REV: R3							

1) Bas

2) Emitter
3) Collector

#### LEAD CODE:

Ver.1.0



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Ver 10